

**Dual P-Ch 30V Fast Switching MOSFETs**

Green Device Available  
 Super Low Gate Charge  
 Excellent CdV/dt effect decline  
 Advanced high cell density Trench technology

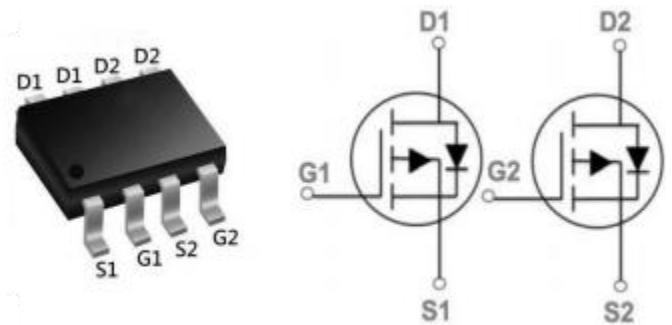
**Product Summary**


BVDSS	RDSON	ID
-30V	18mΩ	-9.5A

**Description**

The XXW4805 is the high cell density trenched P-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The XXW4805 meet the RoHS and Green Product

**SOP8 Pin Configuration**

**Absolute Maximum Ratings** ( $T_A=25^{\circ}\text{C}$  unless otherwise specified)

Symbol	Parameter	Max.	Units
$V_{DSS}$	Drain- Source Voltage	-30	V
$V_{GSS}$	Gate- Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current	$T_A = 25^{\circ}\text{C}$	-9.5
		$T_A = 100^{\circ}\text{C}$	-5.9
$I_{DM}$	Pulsed Drain Current <sup>note1</sup>	-36	A
$E_{AS}$	Single Pulsed Avalanche Energy <sup>note2</sup>	25	mJ
$P_D$	Power Dissipation	$T_A = 25^{\circ}\text{C}$	3.3
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	38	$^{\circ}\text{C}/\text{W}$
$T_J, T_{STG}$	Operating and Storage Temperature Range	-55 to + 150	$^{\circ}\text{C}$

**Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)**

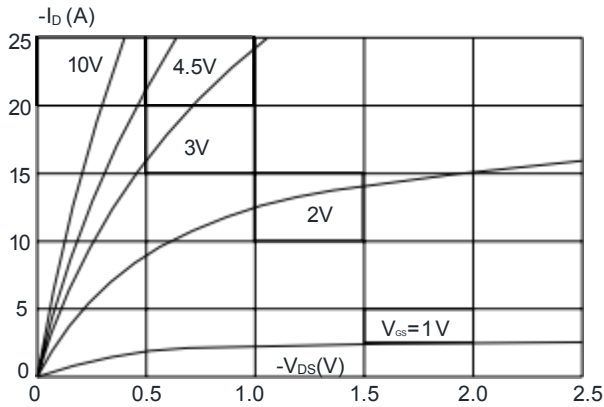
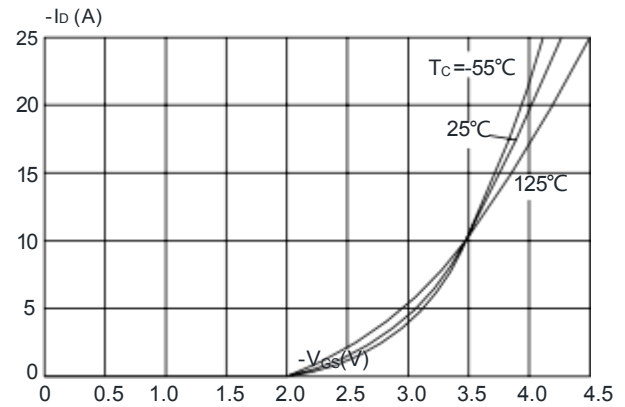
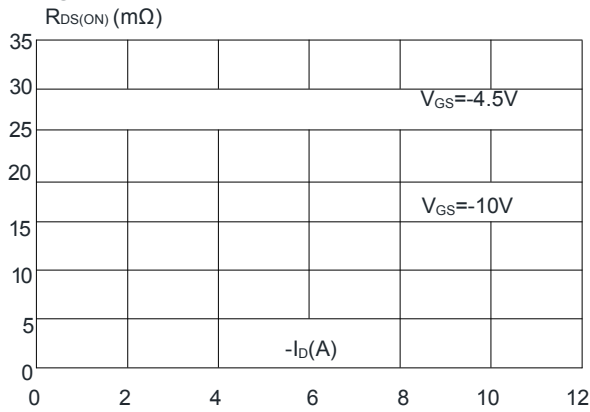
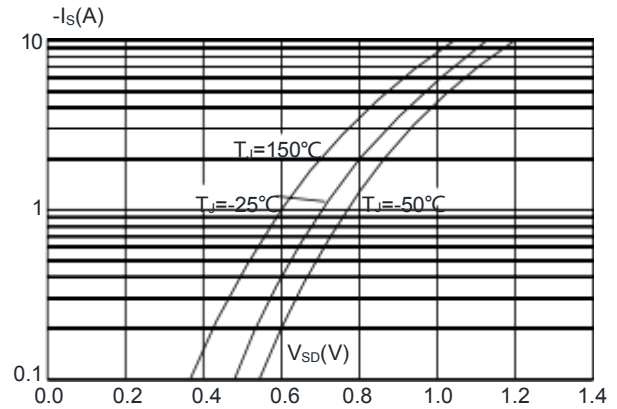
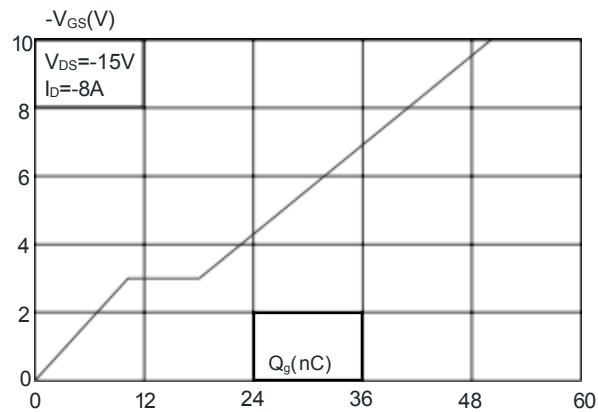
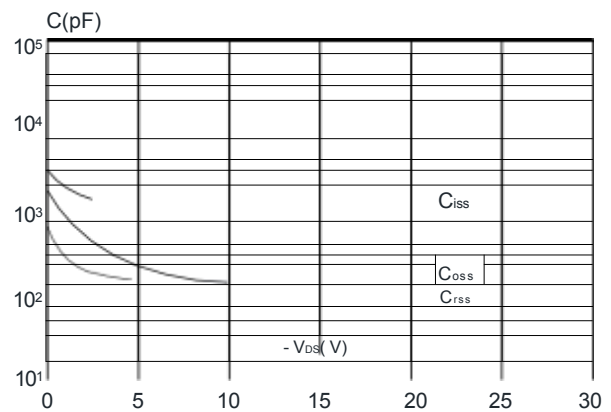
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV <sub>DSS</sub>	Drain- Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =-250uA	-30	---	---	V
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	BV <sub>DSS</sub> Temperature Coefficient	Reference to 25°C , I <sub>D</sub> =- 1mA	---	-0.022	---	V/ °C
R <sub>DS(on)</sub>	Static Drain- Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =- 10V , I <sub>D</sub> =-6A	---	18	25	mΩ
		V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-4A	---	25	42	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =-250uA	-1.0	---	-2.5	V
ΔV <sub>GS(th)</sub>	V <sub>GS(th)</sub> Temperature Coefficient		---	4.6	---	mV/ °C
I <sub>DSS</sub>	Drain- Source Leakage Current	V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C	---	---	-1	uA
		V <sub>DS</sub> =-24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C	---	---	-5	
I <sub>GSS</sub>	Gate- Source Leakage Current	V <sub>GS</sub> = ± 20V , V <sub>DS</sub> =0V	---	---	±100	nA
g <sub>fs</sub>	Forward Transconductance	V <sub>DS</sub> =-5V , I <sub>D</sub> =-6A	---	17	---	S
R <sub>g</sub>	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	---	13	---	Ω
Q <sub>g</sub>	Total Gate Charge (-4.5V)	V <sub>DS</sub> =- 15V , V <sub>GS</sub> =-4.5V , I <sub>D</sub> =-6A	---	12.6	---	nC
Q <sub>gs</sub>	Gate- Source Charge		---	4.8	---	
Q <sub>gd</sub>	Gate- Drain Charge		---	4.8	---	
T <sub>d(on)</sub>	Turn-On Delay Time	V <sub>DD</sub> =- 15V , V <sub>GS</sub> =- 10V , R <sub>G</sub> =3.3Ω , I <sub>D</sub> =-6A	---	4.6	---	ns
T <sub>r</sub>	Rise Time		---	14.8	---	
T <sub>d(off)</sub>	Turn-Off Delay Time		---	41	---	
T <sub>f</sub>	Fall Time		---	19.6	---	
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =- 15V , V <sub>GS</sub> =0V , f=1MHz	---	1345	---	PF
C <sub>oss</sub>	Output Capacitance		---	194	---	
C <sub>rss</sub>	Reverse Transfer Capacitance		---	158	---	

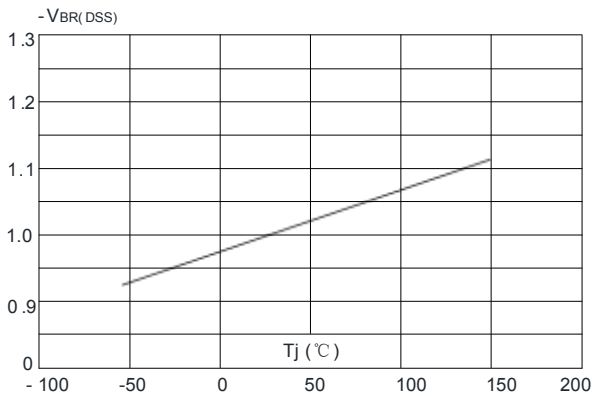
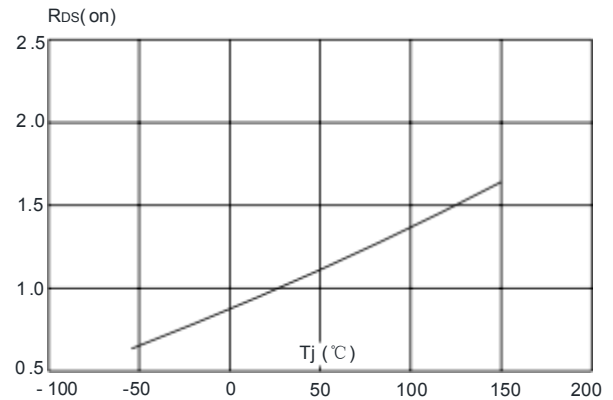
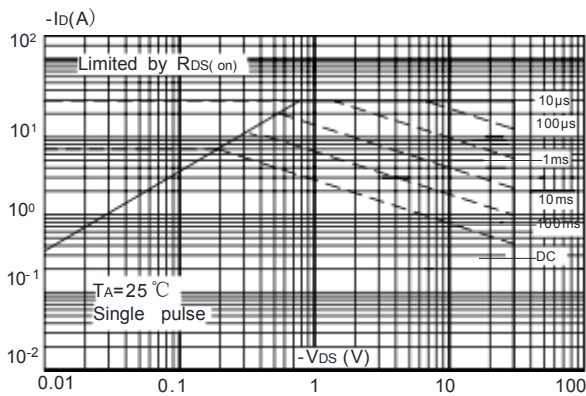
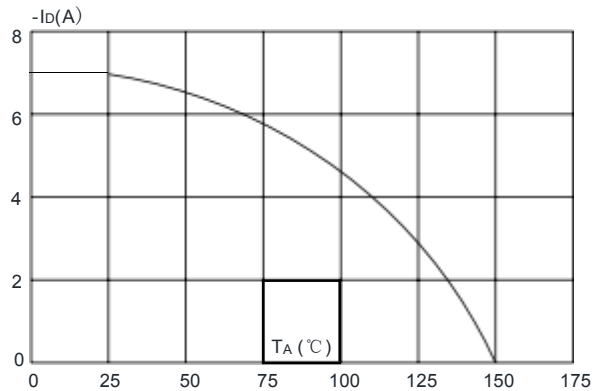
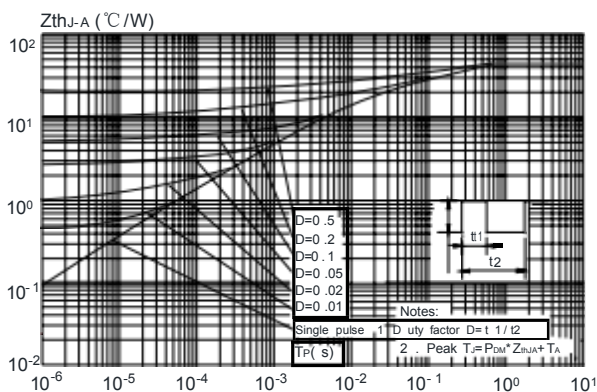
**Diode Characteristics**

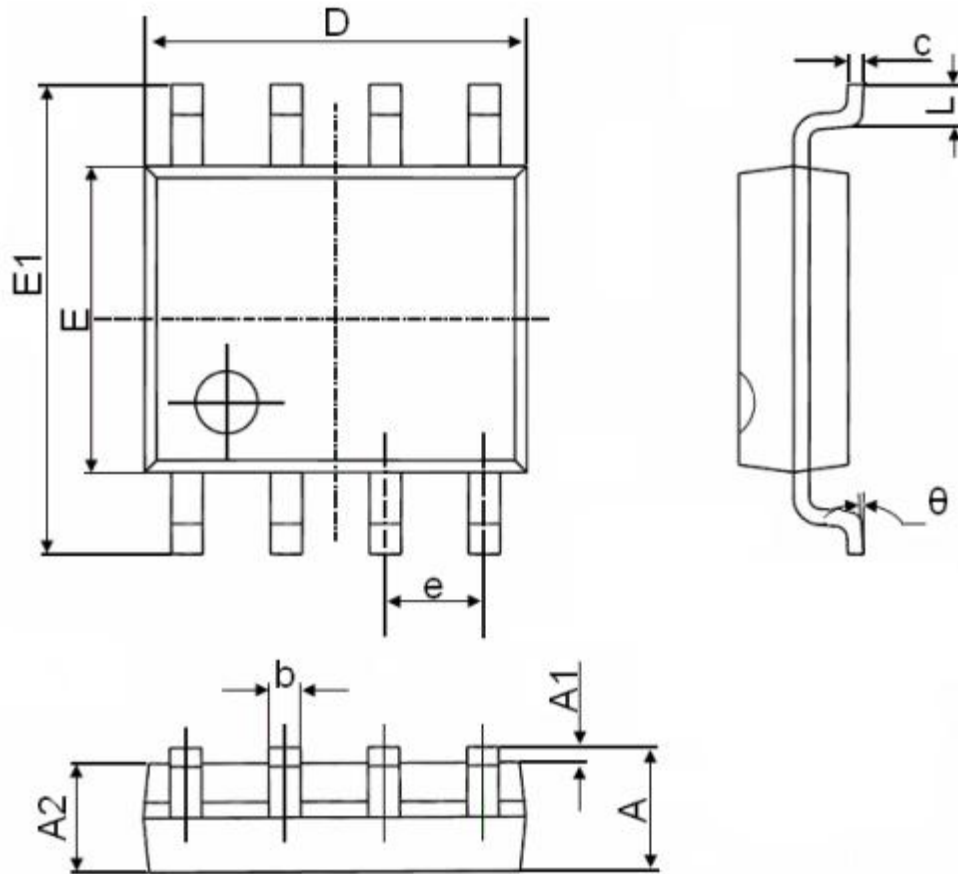
Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current	---	---	-6.5	A
I <sub>SM</sub>	Pulsed Source Current <sup>2,5</sup>		---	---	-26	A
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =- 1A , T <sub>J</sub> =25°C	---	---	-1.2	V
t <sub>rr</sub>	Reverse Recovery Time	I <sub>F</sub> =-6A , dI/dt=100A/μs , T <sub>J</sub> =25°C	---	16.3	---	ns
Q <sub>rr</sub>	Reverse Recovery Charge		---	5.9	---	nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
2. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
3. The EAS data shows Max. rating . The test condition is V<sub>DD</sub>=-25V, V<sub>GS</sub>=- 10V, L=0. 1mH, I<sub>AS</sub>=-38A
4. The power dissipation is limited by 150°C junction temperature
5. The data is theoretically the same as I<sub>D</sub> and I<sub>DM</sub> , in real applications , should be limited by total power dissipation.

**Typical Performance Characteristics**
**Figure 1 : Output Characteristics**

**Figure 2 : Typical Transfer Characteristics**

**Figure 3 : On-resistance vs. Drain Current**

**Figure 4 : Body Diode Characteristics**

**Figure 5 : Gate Charge Characteristics**

**Figure 6 : Capacitance Characteristics**


**Dual P-Ch 30V Fast Switching MOSFETs**
**Figure 7: Normalized Breakdown Voltage vs. Junction Temperature**

**Figure 8: Normalized on Resistance vs. Junction Temperature**

**Figure 9: Maximum Safe Operating Area**

**Figure 10: Maximum Continuous Drain Current vs. Ambient Temperature**

**Maximum Effective Transient Thermal Impedance, Junction-to-Ambient**


**Package Mechanical Data- SOP-8**

 COMMON DIMENSIONS  
(UNITS OF MEASURE=mm)

SYMBOL	MIN	NOM	MAX
A	1.40	1.60	1.80
A1	0.05	0.15	0.25
A2	1.35	1.45	1.55
b	0.30	0.40	0.50
c	0.153	0.203	0.253
D	4.80	4.90	5.00
E	3.80	3.90	4.00
E1	5.80	6.00	6.20
L	0.45	0.70	1.00
$\theta$	2°	4°	6°
L1	1.04 REF		
e	1.27 BSC		
R1	0.07 TYP		
R2	0.07 TYP		